

FIG. 1

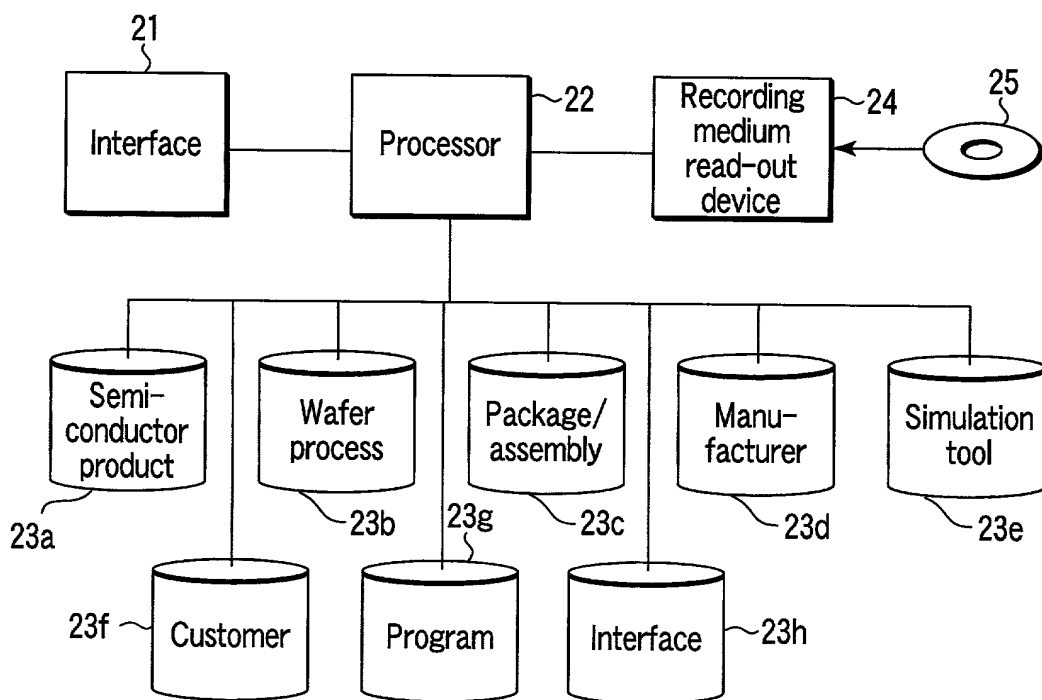


FIG. 2

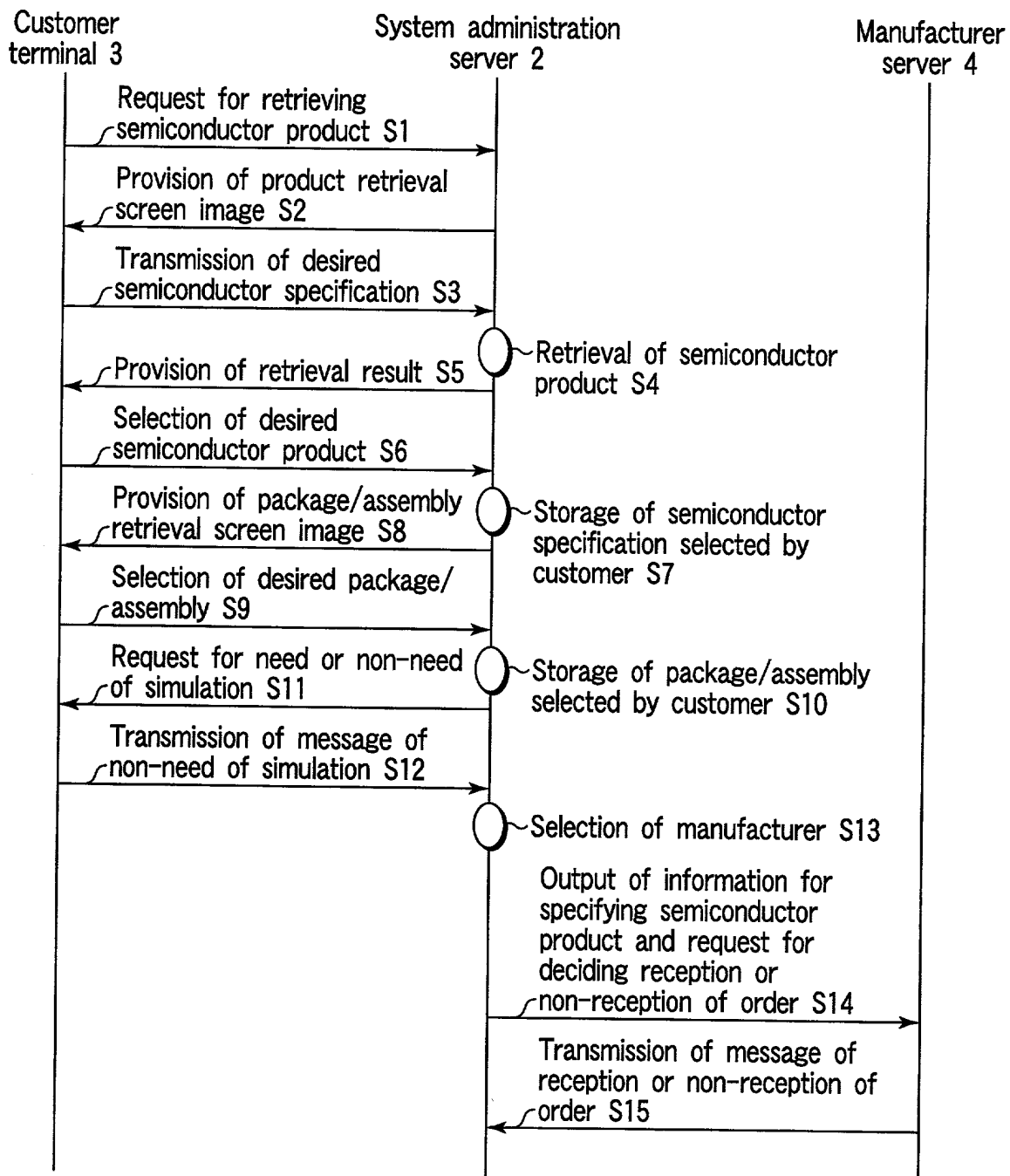


FIG. 3

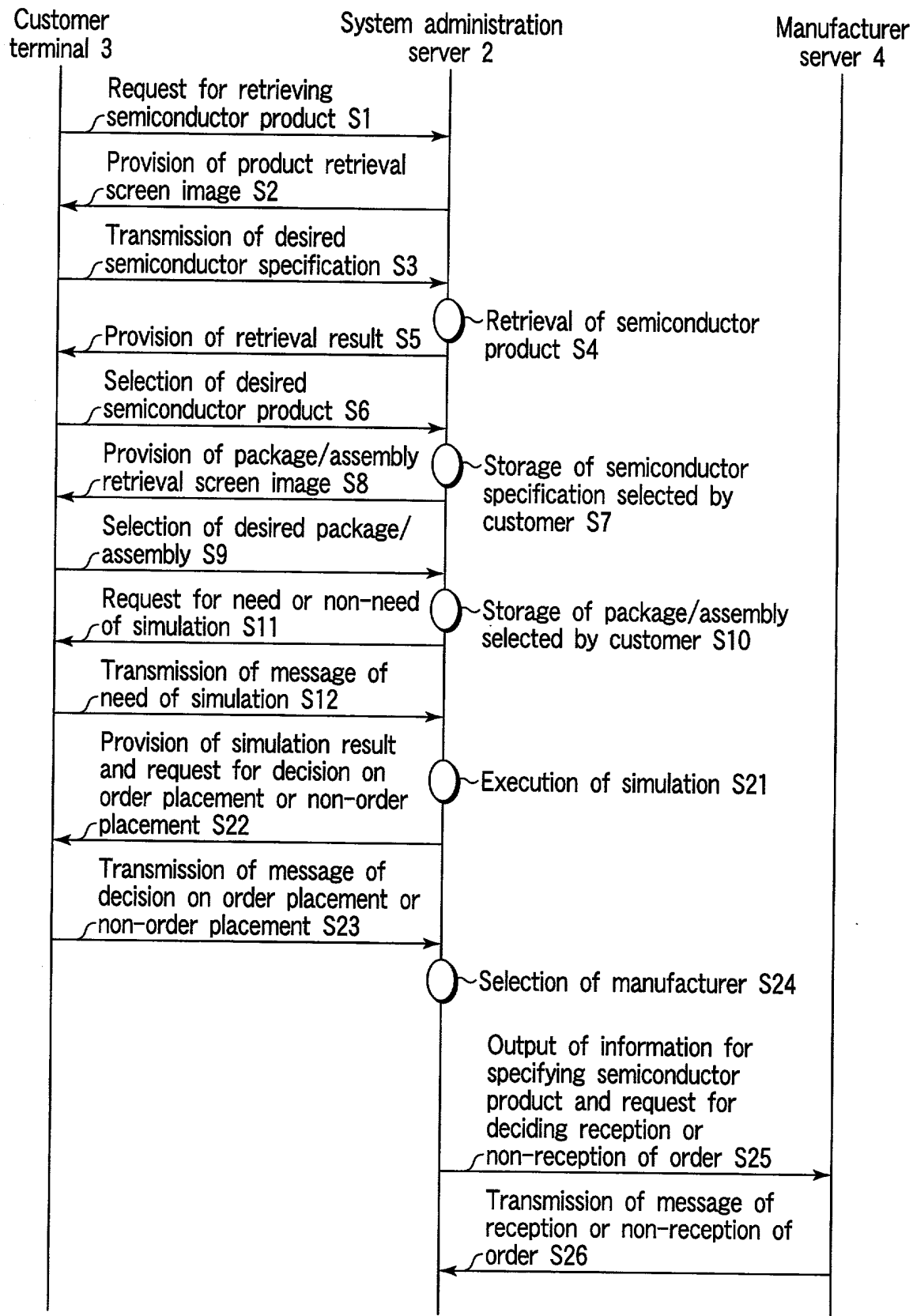


FIG. 4



Select product conforming to your specification form semiconductor products listed below.

System LSI, 800MHz

System LSI, 833MHz

System LSI, 850MHz

OK

Cancel

FIG. 6

Size

External form

Package type

Package structure

Inner lead bonding modes

Packing type for shipment

mm2 ~ mm2

☐BGA    ☐DIP    ☐QFP

☐Single chip    ☐Multi-chip

☐Single layer    ☐Multilayer

☐C4    ☐TAB    ☐Wire

OK

Cancel

FIG. 7

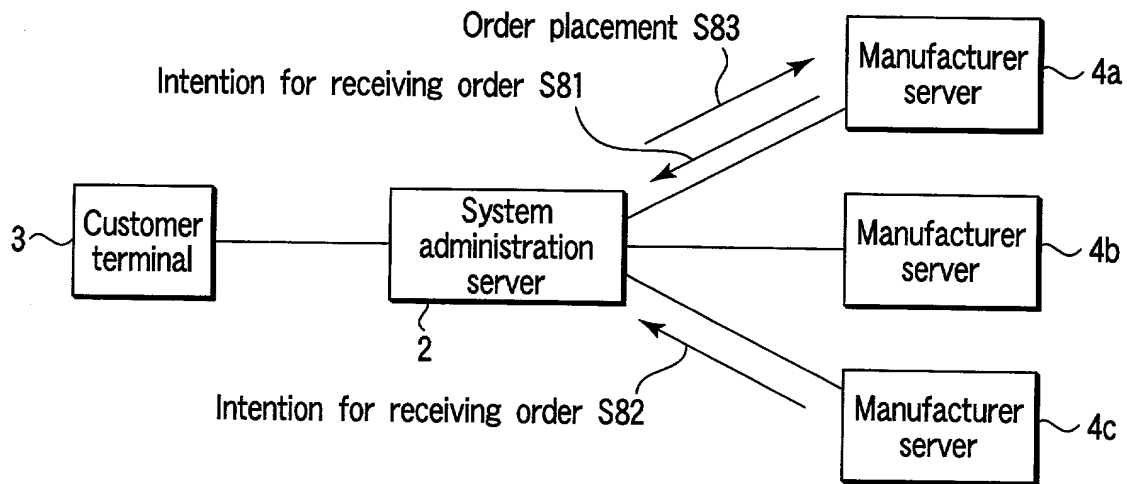


FIG. 8

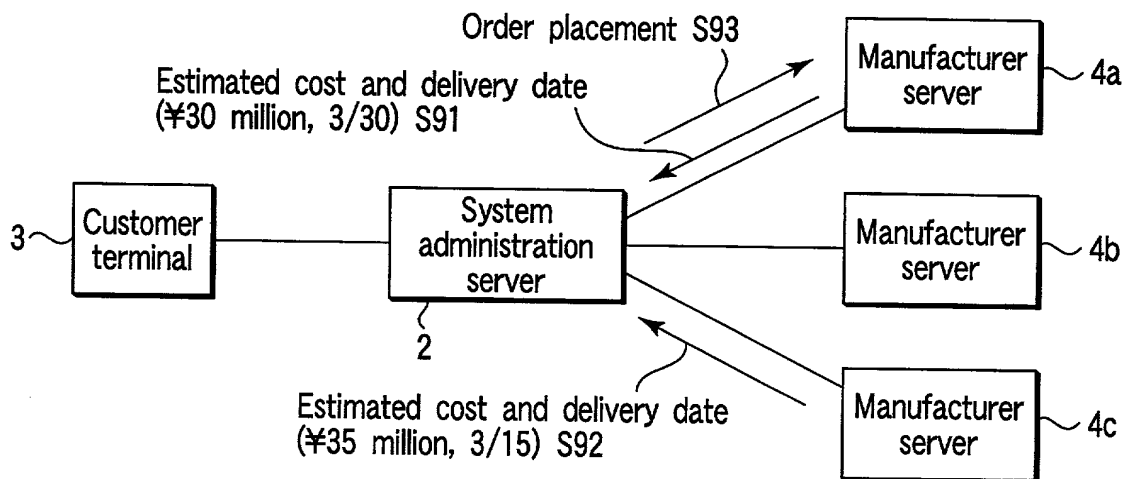


FIG. 9

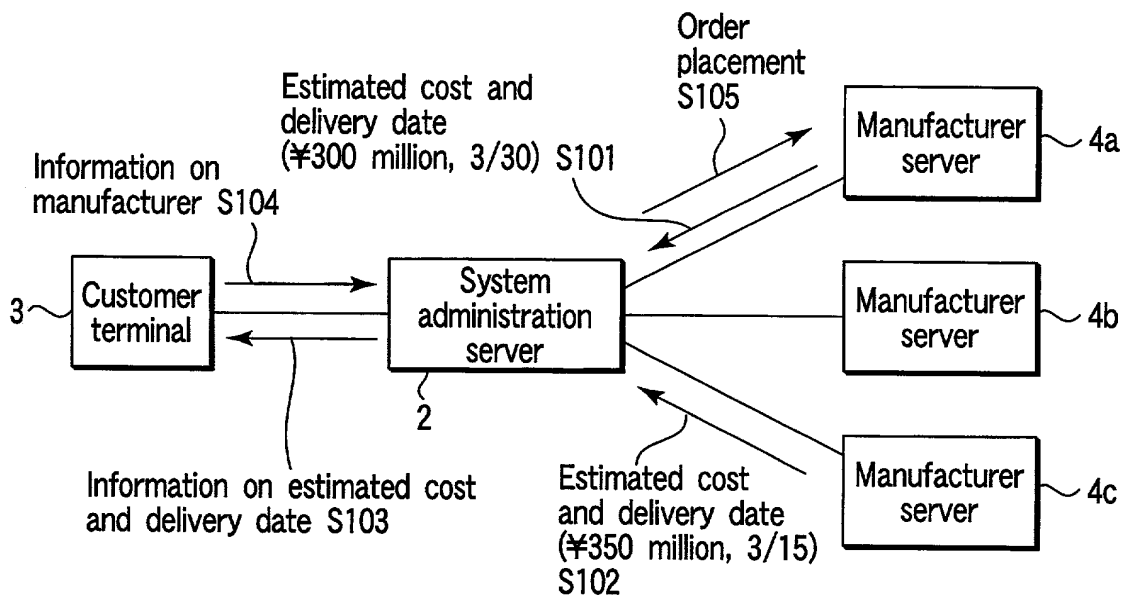


FIG. 10



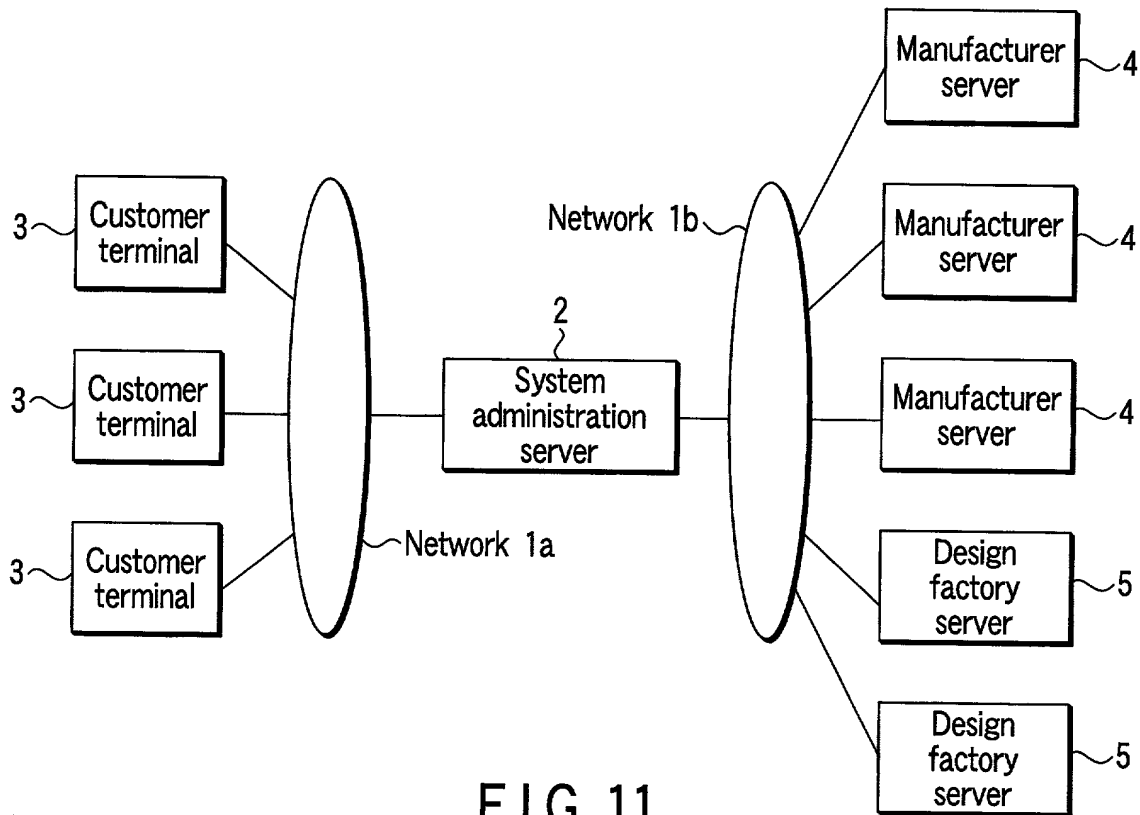


FIG. 11

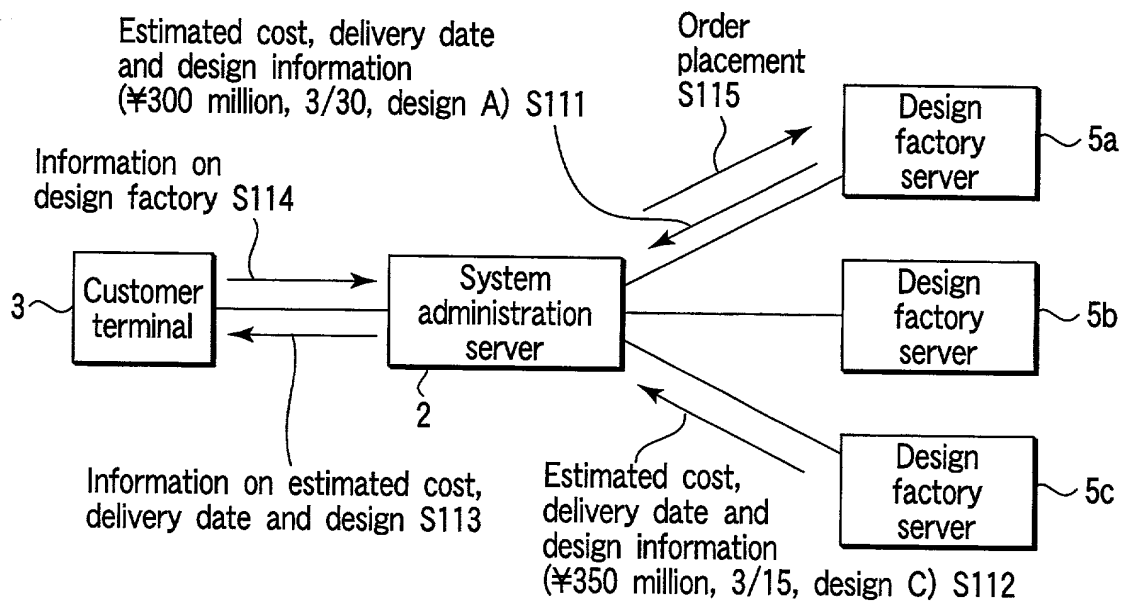


FIG. 12

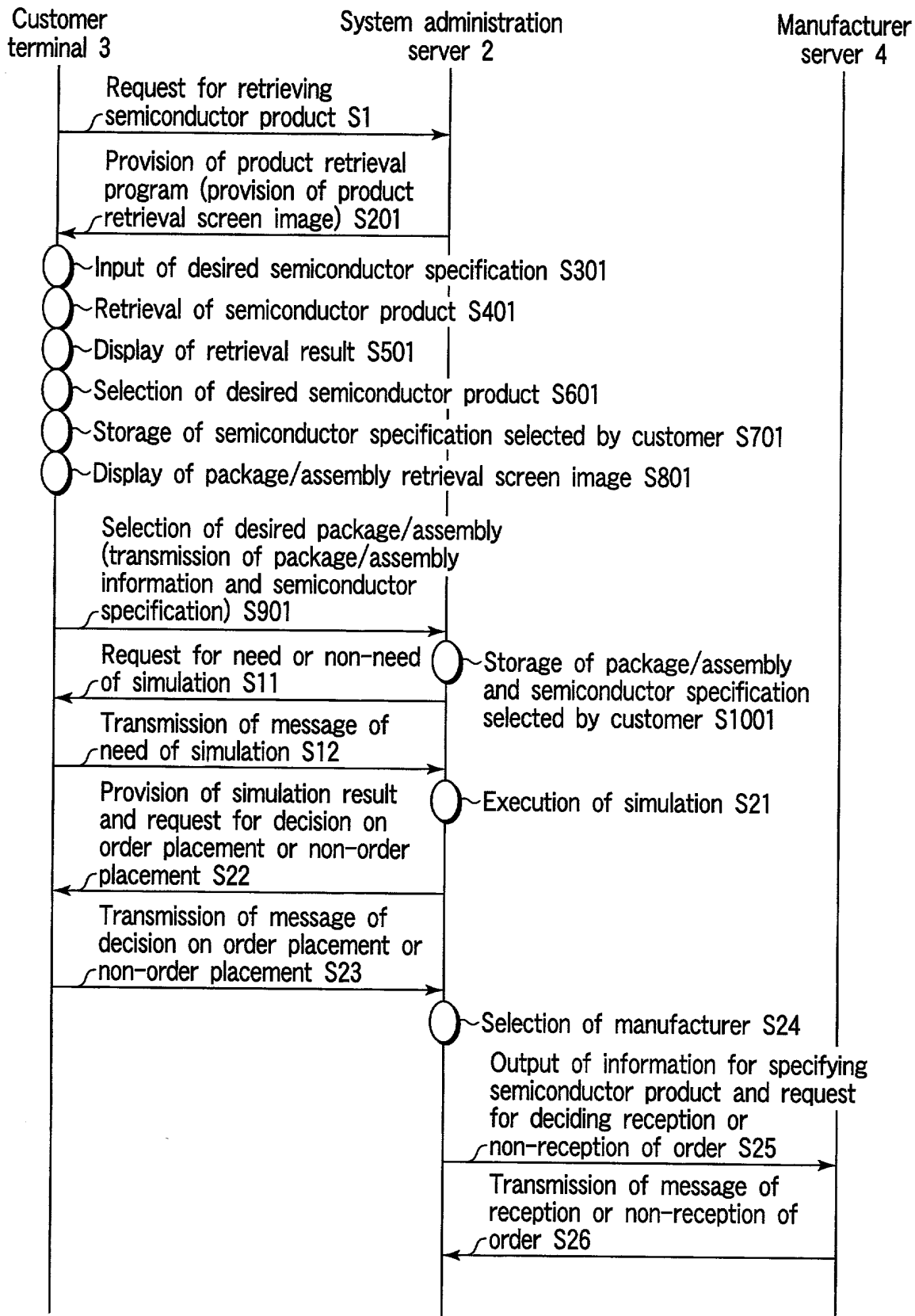


FIG. 13